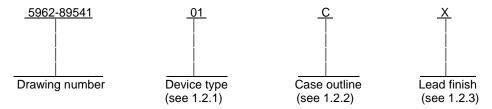
						F	REVISION	SNC										
LTR			-	DESCRI	IPTION	١					DA	DATE (YR-MO-DA)				APPI	ROVED)
А	Drawing upd	ated to refle	ct curre	nt requir	ement	s rc)		01-05-15			R. MONNIN						
'HE ORIGINA	AL FIRST SHEET	OF THIS D	RAWIN	IG HAS I	BEEN	REPL/	ACED.											
	AL FIRST SHEET	OF THIS D	RAWIN	IG HAS I	BEEN	REPLA	ACED.											
REV	AL FIRST SHEET	OF THIS D	RAWIN	IG HAS I	BEEN	REPL/	ACED.											
REV	AL FIRST SHEET	OF THIS D	RAWIN	IG HAS I	BEEN	REPL/	ACED.											
REV SHEET REV	AL FIRST SHEET	OF THIS D	RAWIN	IG HAS I	BEEN	REPLA	ACED.											
REV SHEET REV SHEET		OF THIS D		IG HAS I	BEEN	REPL/	ACED.	A	A	A	A	A	A	A				
REV SHEET REV SHEET REV STATUS	S	RE		IG HAS I				A 4	A 5	A 6	A 7	A 8	A 9	A 10				
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	S	RE SH PRE	V	DBY	A	A	A		5	6	7	8	9	10	col	UMF	BUS	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA	ANDARD	RE SH PRE RIG	V EET EPAREI CK OFF	D BY FICER	A 1	A	A		5	6 EFEN	7 SE SI COL	8 UPPL UMBI	9 Y CE JS, O		4321	6	BUS	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICR DR THIS DRAW FOR I	ANDARD OCIRCUIT RAWING	RE SH PRE RIC	V EET EPAREICK OFF ECKED BARLES	D BY FICER BY S E. BES	A 1	A	A	4 MIC	DE CROC	6 EFEN	SE SI COLI	UPPL UMBI o://ww	y CE JS, O w.ds	10 NTER	4321(a.mil DRO	6 OP-F	RATE	,
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICR DR THIS DRAW FOR I DEP/ AND AGE	ANDARD OCIRCUIT RAWING	RE SH PRE RIG	EET EPAREICK OFF ECKED HARLES	D BY FICER BY S E. BES	A 1 SORE	A 2	A	MIC ACC	DE CROC	6 EFEN: CIRCUATE S	FE SI COLUMN THE PROPERTY OF T	UPPL UMBI o://ww	9 Y CE JS, O vw.ds	NTER	4321(a.mil DRO	6 OP-F	RATE	,

1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
 - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	SMP-11A	Low-droop-rate, accurate sample and hold amplifier
02	SMP-11B	Low-droop-rate, accurate sample and hold amplifier
03	SMP-10A	Low-droop-rate, accurate sample and hold amplifier
04	SMP-10B	Low-droop-rate, accurate sample and hold amplifier

1.2.2 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	<u>Descriptive designator</u>	<u>Terminals</u>	Package style
С	GDIP1-T14 or CDIP2-T14	14	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings.

Positive supply voltage (+V _S)	. +18 V dc
Negative supply voltage (-Vs)	18 V dc
Power dissipation (P _D)	. 500 mW
For cases C and 2, derate above T _A = 100°C	. 10 mW /°C
Input voltage (V _{IN})	. Equal to supply voltage
Logic and logic reference voltage	
Output short-circuit duration	. Indefinite
Hold capacitor short-circuit duration	. 60 seconds
Junction temperature (T _J)	
Storage temperature range	65°C to +150°C
Lead temperature (soldering, 10 seconds)	. +300°C
Thermal resistance, junction-to-case (θ_{JC})	. See MIL-STD-1835
Thermal resistance, junction-to-case (θ _{JA}):	
Case C	. 100°C/W
Case 2	. 110°C/W

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89541
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL A	SHEET 2

1.4 Recommended operating conditions.

Positive supply voltage range (+V _S)	+15 V dc
Negative supply voltage range (-Vs)	-15 V dc
Hold capacitor (C _H)	0.005 μF
Logic control (V _{LC})	Connected to ground, or 3.5 V below positive supply
	and 2.0 V above negative supply
Ambient operating temperature range (T _A)	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

STANDARD MICROCIRCUIT DRAWING

SIZE A		5962-89541
	REVISION LEVEL A	SHEET 3

- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
 - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.5.1 <u>Certification/compliance mark.</u> A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89541
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL A	SHEET 4

TABLE I. <u>Electrical performance characteristics</u>.

Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C unless otherwise specified	Group A subgroups	Device type	Lir	nits	Unit
					Min	Max	1
Zero scale error (hold mode)	Vzs	V _{S/H} = 3.5 V (500 μs after	1	01,03		+1.5	mV
		hold), V _{IN} = 0 V	2,3			+3.0	
			1	02,04		+3.0	
			2,3			+5.5	
Input bias current	I _{IB}	V _{IN} = 0 V	1	01,03		±65	nA
			2,3			±180	
			1	02,04		±90	_
			2,3			±280	
Input voltage range or output voltage swing	Vsw	$R_L = 2.5 \text{ k}\Omega$	1	01,03	±11		V
			2,3		±10.5		_
			1,2,3	02,04	±10.5		
Power supply rejection (sample mode)	PSR	$+V_S = +9 \text{ V to } +18 \text{ V},$	1	01,03	82		dB
		$-V_S = -9 \text{ V to } -18 \text{ V}$	2,3		78		
			1	02,04	77		
			2,3		72		
Differential logic threshold	VTH		1	All	8.0	2.0	V
			2,3		0.6	2.0	
Logic control input current	ILC	V _{LC} = 0 V	1	01,03		-2	μΑ
			2,3			-3	
			1	02,04		-3	_
			2,3			-5	

See footnotes at end of table.

STANDARD
MICROCIRCUIT DRAWING

SIZE A		5962-89541
	REVISION LEVEL A	SHEET 5

TABLE I. <u>Electrical performance characteristics</u> – Continued.

Test	Symbol			Device type	Liı	mits	Unit
					Min	Max	
Supply current	Isy		1	01,03	2.0	6.0	mA
			2,3		2.0	8.4	
			1	02,04	2.0	7.0	
			2,3		2.0	8.4	
Logic input current (sample mode)	I _{S/H}	V _{S/H} = 0.6 V	1,2,3	All		-15	μΑ
Logic input current (hold mode)	I _{S/H}	V _{S/H} = 5 V	1,2,3	All	-1	1	μΑ
Droop rate	dV _{CH} /		4	01		200	μV/ms
	dt		5	•		4000	
			6	•		1500	
			4	02		500	
			5	•		5000	
			6	•		2000	
			4	03		20	
			5			4000	1
			6			100	1
			4	04		50	1
			5			5000	1
			6			250	1

See footnotes at end of table.

STANDARD		
MICROCIRCUIT DRAWING		

SIZE A		5962-89541
	REVISION LEVEL A	SHEET 6

TABLE I. <u>Electrical performance characteristics</u> – Continued.

Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C unless otherwise specified	Group A subgroups	Device type	Lim	its	Unit
					Min	Max	
Leakage (droop) current	I _{DR}		4	01		1.0	μA/ms
			5			20.0	1
			6	1		7.5	
			4	02		2.5	
			5			25.0	
			6	-		10.0	
			4	03		0.10	
			5	1		20.0	1
			6	1		0.5	
			4	04		0.25	1
			5			25.0	
			6			1.22	
Voltage gain (sample mode)	A _V	$V_{IN} = \pm 10 \text{ V}, R_L = 5 \text{ k}\Omega$	4	01,03	0.99963		V/V
(or	5,6		0.99950		
		$V_{IN} = \pm 5 \text{ V}, R_L = 2.5 \text{ k}\Omega$	4	02,04	0.99953		
			5,6		0.99940		
Hold capacitor charging current	+l _{CH}	V _{IN} − V _{OUT} ≥ +3 V	4,5,6	01,03	20		mA
				02,04	15		1
	-I _{CH}	V _{IN} − V _{OUT} ≤ -3 V	1	01,03	-20		
				02,04	-15		
Sample / Hold current ratio	I _{CH} /		1,2,3	01,02	2x10 ⁶		mA/mA
	I _{DR}			03,04	0.6x10 ⁶		

 $[\]underline{1}$ / Unless otherwise specified, +V_S = +15 V, -V_S = -15 V, C_H = 5000 pF, and V_{LC} = connected to ground.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89541
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL A	SHEET 7

Device types	01, 02, 03, and 04		
Case outlines	С	2	
Terminal number	Terminal symbol		
1	NC <u>1</u> /	NC	
2	INPUT	NC	
3	NULL	INPUT	
4	NULL	NULL	
5	-V _S	NC	
6	NC	NULL	
7	OUTPUT	NC	
8	NC <u>1</u> /	-V _S	
9	+V _S	NC	
10	NC	OUTPUT	
11	Сн	NC	
12	NC	NC	
13	VLC	+Vs	
14	S/H <u>2/</u>	NC	
15		NC	
16		Сн	
17	NC		
18	NC		
19		V _{LC}	
20	S/H <u>2</u> /		

^{1/} Pins 1 and 8 are not internally connected.

2/ Sample / Hold control

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89541
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL A	SHEET 8

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*,2,3,4,5,6
Group A test requirements (method 5005)	1,2,3,4,5,6
Groups C and D end-point electrical parameters (method 5005)	1

^{*} PDA applies to subgroup 1. For device types 01 and 03, Vzs is excluded from PDA.

- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
 - 5. PACKAGING
 - 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89541
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL A	SHEET 9

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0547.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING

SIZE A		5962-89541
	REVISION LEVEL A	SHEET 10

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 01-05-15

Approved sources of supply for SMD 5962-89541 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8954101CA	<u>3</u> /	SMP-11AY/883
5962-8954102CA	24355	SMP-11BY/883
5962-89541022A	24355	SMP-11BRC/883
5962-8954103CA	<u>3</u> /	SMP-10AY/883
5962-8954104CA	<u>3</u> /	SMP-10BY/883
5962-89541042A	<u>3</u> /	SMP-10BRC/883

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGEVendor namenumberand address

24355

Analog Devices

Route 1 Industrial Park
P.O. Box 9106

Norwood, MA 02062

Point of contact: 1500 Space Park Drive P.O. Box 58020 Santa Clara, CA 95050-8020

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.